

Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions		Min	Тур	Max	Units
STATIC F	PARAMETERS						
BV _{DSS}	Drain-Source Breakdown Voltage	I _D =10mA, V _{GS} =0V		75			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =75V, V _{GS} =0V				1	μA
			T _J =55°C			5	μΑ
I _{GSS}	Gate-Body leakage current	V_{DS} =0V, V_{GS} = ±25V				100	nA
V _{GS(th)}	Gate Threshold Voltage	$V_{DS}=V_{GS}$ I _D =250µA		1	2.3	3	V
I _{D(ON)}	On state drain current	V _{GS} =10V, V _{DS} =5V		15			Α
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V, I _D =3.1A			105	130	mΩ
			T _J =125°C		158	195	
		V _{GS} =4.5V, I _D =2A			126	165	mΩ
g _{FS}	Forward Transconductance	V _{DS} =5V, I _D =3.1A			10		S
V _{SD}	Diode Forward Voltage	I _S =1A,V _{GS} =0V			0.77	1	V
I _S	Maximum Body-Diode Continuous Curr	rent				2.5	Α
DYNAMIC	PARAMETERS						
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =30V, f=1MHz			290	380	pF
C _{oss}	Output Capacitance				54		pF
C _{rss}	Reverse Transfer Capacitance				24		pF
R _g	Gate resistance	V _{GS} =0V, V _{DS} =0V, f=1MHz			2.4	3.5	Ω
SWITCHI	NG PARAMETERS						
Q _g (10V)	Total Gate Charge	V _{GS} =10V, V _{DS} =30V, I _D =3.1A			5.14	7	nC
Q _g (4.5V)	Total Gate Charge				2.34		nC
Q _{gs}	Gate Source Charge				0.97		nC
Q_{gd}	Gate Drain Charge				1.18		nC
t _{D(on)}	Turn-On DelayTime	V _{GS} =10V, V _{DS} =30V, R _L =9.7Ω, R _{GEN} =3Ω			4		ns
t _r	Turn-On Rise Time				3.4		ns
t _{D(off)}	Turn-Off DelayTime				14.4		ns
t _f	Turn-Off Fall Time				2.4		ns
t _{rr}	Body Diode Reverse Recovery Time	I _F =3.1A, dl/dt=100A/μs			30.2	45	ns
Q _{rr}	Body Diode Reverse Recovery Charge	I _F =3.1A, dI/dt=100A/μs			21.5		nC

A: The value of R $_{0JA}$ is measured with the device mounted on 1in ² FR-4 board with 2oz. Copper, in a still air environment with T $_{A}$ =25°C. The value in any given application depends on the user's specific board design. The current rating is based on the t ≤10s thermal resistance rating. B: Repetitive rating, pulse width limited by junction temperature.

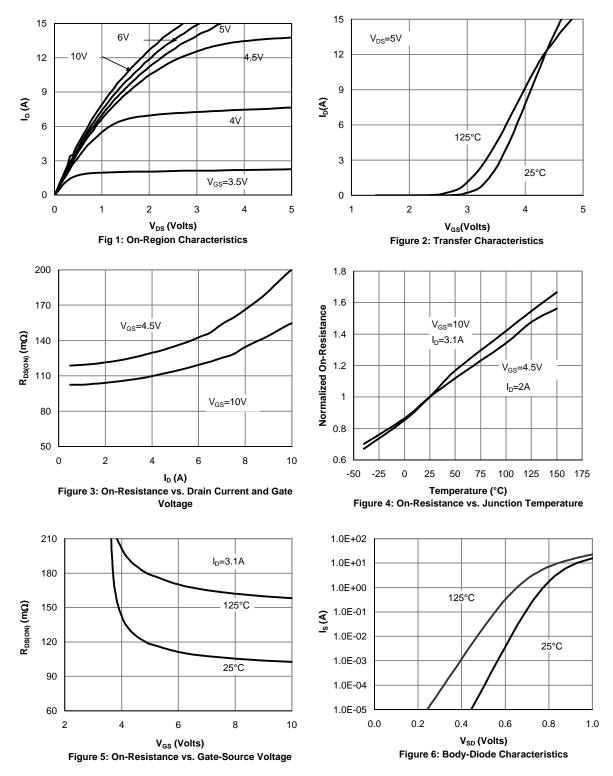
C. The R $_{\rm \theta JA}$ is the sum of the thermal impedence from junction to lead R $_{\rm \theta JL}$ and lead to ambient.

D. The static characteristics in Figures 1 to 6 are obtained using $<300 \ \mu s$ pulses, duty cycle 0.5% max.

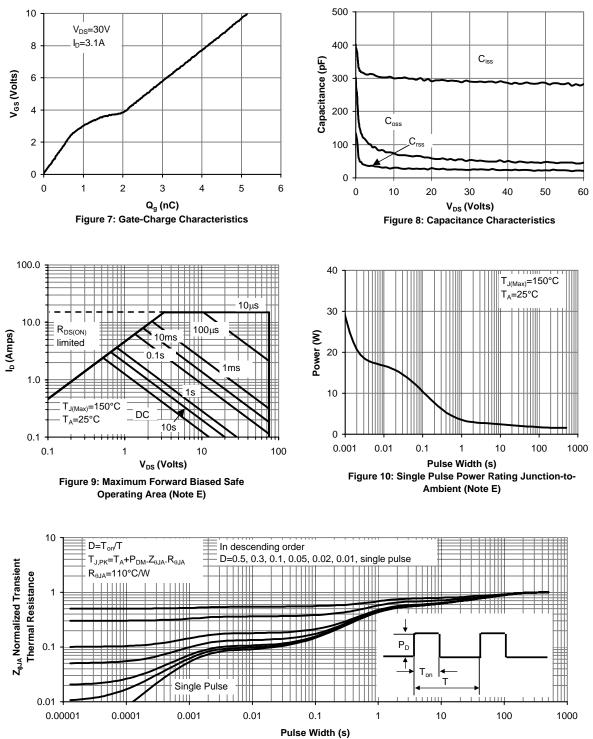
E. These tests are performed with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with T _A=25°C. The SOA curve provides a single pulse rating.

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS



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Figure 11: Normalized Maximum Transient Thermal Impedance

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